Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S3	62677	((PWB or PCB or board or substrate) with (pad$1 or land$1)).ab,clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/24 15:25
S4	843	((PWB or PCB or board or substrate) with (pad adj layout or land adj pattern$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/24 15:26
S5	53	S4 and ((shape) with (pad adj layout or land adj pattern$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/24 15:31
S6	43	S3 and ((shape) with (pad adj layout or land adj pattern$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/24 15:29
S7	7	S6 not S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/24 15:30
S29	16605	(pad or land) with (layout or pattern)	US-PGPUB; USPAT	OR	OFF	2005/04/28 10:08
S30	11296	(pad or land) with (layout or pattern)	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 10:09
S31	5630	S29 and array	US-PGPUB; USPAT	OR	OFF	2005/04/28 10:08
S32	704	S30 and (array)	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 10:09
S33	6334	S31 or S32	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 10:10

S34	1036	S33 and ((pad or land) with (shape or lobe))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 10:48
S35	12	(pad adj layout) with (board or substrate) with (array)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 12:46
S36	15	(land adj pattern) with (board or substrate) with (array)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 12:47
S37	601	(land or lands or pad or pads) with (lobe)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 12:49
S38	84	S37 and (pwb or pcb or board or substrate or package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 12:52
S58	60698	"174"/$.ccls.	US-PGPUB; USPAT	OR	OFF	2005/04/28 15:09
S59	128769	"29"/$.ccls.	US-PGPUB; USPAT	OR	OFF	2005/04/28 15:10
S60	86295	"361"/$.ccls.	US-PGPUB; USPAT	OR	OFF	2005/04/28 15:10
S61	169086	"257"/$.ccls.	US-PGPUB; USPAT	OR	OFF	2005/04/28 15:10
S62	32606	"333"/$.ccls.	US-PGPUB; USPAT	OR	OFF	2005/04/28 15:10
S63	437057	S58 or S59 or S60 or S61 or S62	US-PGPUB; USPAT	OR	OFF	2005/04/28 15:33
S64	207	S63 and (CCGA or column adj grid adj array)	US-PGPUB; USPAT	OR	OFF	2005/04/28 15:28
S65	615	(CCGA or column adj grid adj array)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 15:28

S66	408	S65 not S64	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 15:28
S67	4272	S63 and ((solder) adj (mask or resist))	US-PGPUB; USPAT	OR	OFF	2005/04/28 15:34
S68	3687	S67 and (pad or pads or land or lands or interconnect or interconnects)	US-PGPUB; USPAT	OR	OFF	2005/04/28 15:35
S69	693	S67 and ((pad or pads or land or lands or interconnect or interconnects) with (layout or arrangement))	US-PGPUB; USPAT	OR	OFF	2005/04/28 16:34
S70	3386	((pcb or pwb or board or sustratre) with (pad or pads or land or lands) with (arra$6)).clm,ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 16:37
S71	628	S70 and (bga or ball adj grid adj array)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/28 17:08
S72	3542	(board or substrate) and ((pad or pads or land or lands) with (projection$1 or extention$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/29 12:36
S73	1242	(board or substrate) and ((pad or pads or land or lands) near3 (projection$1 or extention$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/29 12:37
S74	454	S72 and ((pad or pads or land or lands) with (arrangement$1 or layout$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/29 12:38
S75	194	S73 and S74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/29 12:47

S77	92	(pad adj layout) with (board or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/29 12:51
S79	681	(contac adj pad$1 or bond adj pad$1) with (projection$1 or protrusion$1 or projected or extension or extended)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/29 13:49
S80	435	(solder) with (ball) with (mounting) with (pad or pads)	US-PGPUB; USPAT	OR	OFF	2005/04/29 13:51
S81	248	S80 and (mask or resist)	US-PGPUB; USPAT	OR	OFF	2005/04/29 13:59
S83	2649	(land or lands or pad or pads) near3 (tab or tabs)	US-PGPUB; USPAT	OR	OFF	2005/05/01 17:13
S84	1634	(land or lands or pad or pads) near2 (tab or tabs)	US-PGPUB; USPAT	OR	OFF	2005/05/01 17:13
S85	687	(land or lands or pad or pads) near1 (tab or tabs)	US-PGPUB; USPAT	OR	OFF	2005/05/01 17:14
S86	444	(land or lands or pad or pads) adj (tab or tabs)	US-PGPUB; USPAT	OR	OFF	2005/05/01 17:15
S87	174105	(pwb or pcb or wiring adj board or circuit adj board)	US-PGPUB; USPAT	OR	OFF	2005/05/01 17:48
S88	158	S86 and S87	US-PGPUB; USPAT	OR	OFF	2005/05/01 17:26
S89	238	S85 and S87	US-PGPUB; USPAT	OR	OFF	2005/05/01 17:32
S90	80	S89 not S88	US-PGPUB; USPAT	OR	OFF	2005/05/01 17:32
S91	502	S84 and S87	US-PGPUB; USPAT	OR	OFF	2005/05/01 17:40
S92	264	S91 not (S89 or S88)	US-PGPUB; USPAT	OR	OFF	2005/05/01 17:41
S93	813	S83 and S87	US-PGPUB; USPAT	OR	OFF	2005/05/01 17:40
S94	391	S93 not (S91 not S89 or S88)	US-PGPUB; USPAT	OR	OFF	2005/05/01 17:48
S95	5535	((pwb or pcb or wiring adj board or circuit adj board))	USOCR; IBM_TDB	OR	OFF	2005/05/01 17:51
S96	2	S95 and (land or lands or pad or pads) adj (tab or tabs)	USOCR; IBM_TDB	OR	OFF	2005/05/01 17:50
S97	14	S95 and (land or lands or pad or pads) near3 (tab or tabs)	USOCR; IBM_TDB	OR	OFF	2005/05/01 17:51

S98	236938	((pwb or pcb or wiring adj board or circuit adj board))	EPO; JPO; DERWENT	OR	OFF	2005/05/01 17:51
S99	54	S98 and ((land or lands or pad or pads) near3 (tab or tabs))	EPO; JPO; DERWENT	OR	OFF	2005/05/01 17:55
S10 0	170	S98 and ((land or lands or pad or pads) with (tab or tabs))	EPO; JPO; DERWENT	OR	OFF	2005/05/01 17:55
S10 1	7726	S100 ot S99	EPO; JPO; DERWENT	OR	OFF	2005/05/01 17:56
S10 2	116	S100 not S99	EPO; JPO; DERWENT	OR	OFF	2005/05/01 18:01
S12 0	681	S118 and bga	US-PGPUB; USPAT	OR	OFF	2005/05/02 13:18
S12 1	78	solder adj mask adj defined	US-PGPUB; USPAT	OR	OFF	2005/05/03 11:04
S12 2	13	solder adj mask adj defined	EPO; JPO; DERWENT	OR	OFF	2005/05/03 11:06